

Quarterly Reliability Monitoring Results

Quarters: Q1/2022 to Q4/2023

Based on structural similarity

| Supplier Nexperia B.V. Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test | | User Part Number | | | | | | |
|--|----------------------------------|---|-------------|-----------|------------|-----------|--|--|
| | | PMEG40T10ER-Q | | | | | | |
| | | Part Description | | | | | | |
| | | Nexperia DHAM | Schottky | | | | | |
| | | SMD package | | | | | | |
| | | Test Conditions | Duration | # Lots | # Quantity | # Rejects | | |
| | TEST | | | | | | | |
| | Pre- and Post-Stress | | | | | | | |
| # E1 | Electrical Test | Tamb = 25 °C | N/A | see below | all parts | see below | | |
| | | JESD22-A113 | | | | | | |
| | | Bake Tamb = 125 °C | 24 hours | | | | | |
| | PC | Soak Tamb = 85 °C, RH = 85% | 168 hours | | | | | |
| # A1 | Preconditioning | Reflow soldering | 3 cycles | 1514 | 64430 | 0 | | |
| | | MIL-STD-750-1 | | | | | | |
| | HTRB | M1038 Method A | | | | | | |
| | 3 | Tj = Tjmax, $Vr = 100%$ of max. datasheet | | | | | | |
| # B1 | Bias | reverse voltage ^[1] | 1000 hours | 206 | 9320 | 0 | | |
| | | | | | | | | |
| | TC | JESD22-A104 | | | | _ | | |
| # A4 | Temperature Cycling | -65 °C to Tjmax, not to exceed 150°C | 1000 cycles | 311 | 14080 | 0 | | |
| | | JECD22 4440 | | | | | | |
| # 42 | UHAST Unbiased HAST | JESD22-A118 | | | | | | |
| # A3 or | Undiased HAST | Tamb = 130 °C, RH = 85 % | 96 hours | 311 | 14080 | 0 | | |
| | | JESD22-A102 | | | | | | |
| | AC | Tamb = 121 °C, RH = 100 % | | | | | | |
| # A3 alt | Autoclave | Pressure = 205 kPa (29.7 psia) | | | | | | |
| | | JECD22 A101 | | | | | | |
| | H3TRB | JESD22-A101 Tamb = 85 °C, RH = 85%, VR = 80 % of | | | | | | |
| " * O !! | High Humidity High | rated reverse voltage ^{[1], [2]} | 10001 | 244 | 4 4000 | • | | |
| # A2 alt | Temperature Reverse Bias | | 1000 hours | 311 | 14080 | 0 | | |
| | | MIL-STD-750 Method 1037 | | | | | | |
| # A.F | IOL | ton = toff, devices powered to insure ΔTj = | 1000 5 | 212 | 14120 | 0 | | |
| # A5 | Intermittent Operating Life | 100 °C for 15000 cycles | 1000 hours | 312 | 14120 | 0 | | |
| | neu | JECD22 A111 | | | | | | |
| # C0 | RSH Resistance to Solder Heat | JESD22-A111 | 10 - | 260 | 0070 | 0 | | |
| # C8 | | 200 -C = 3 -C | 10 s | 269 | 8070 | 0 | | |
| # C10 | SD Solderability | J-STD-002 | | 222 | 6660 | 0 | | |
| # C10 | Soluerability | J-31D-002 | | 222 | UDDU | U | | |

^[1] The physical limitations of Schottky diodes have to be considered (thermal runaway).

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

| Wafer Fab | Technology | Quantity | Rejects | Failure Rate (FIT) | MTTF (hrs) |
|-----------|------------|----------|---------|--------------------|------------|
| Nexperia | | | | | |
| DHAM | Schottky | 9320 | 0 | 0,46 | 2,19E+09 |

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^[2] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.